

II. SPECIFICATION AMENDMENTS

Please replace the paragraph/section beginning on page 3, line 10, through page 3, line 25 as rewritten below:

FIG. 2 is an exploded view of a semiconductor cassette reducer 20 in accordance with one embodiment of the invention. The semiconductor cassette reducer 20 has a first substantially U-shaped plate 22 and a second substantially U-shaped plate 24. A plurality of wafer supports 26, 28, 30, 32 connect the first substantially U-shaped plate 22 [[longitudinally]] to the second substantially U-shaped plate 24 as shown in Fig. 3. In one embodiment screws 34 and washers 36 are used to attach the U-shaped plates 22, 24 to the wafer supports 26, 28, 30, 32. Retention springs (plurality of retention springs, more than two retention springs, flexible disks) 38 are attached to the first U-shaped plate 22 and the second U-shaped plate 24. In one embodiment, the retention springs 38 are attached using screws 40. In one embodiment, the retention springs are formed of a rubbery substance that is deformable. When the cassette reducer 20 is placed (in the direction indicated by arrow 52S in Fig. 1) in the FOUP the retention springs 38 (which as shown in Fig. 3 project [[laterally from]] beyond lateral peripheral edges of plates 22, 24) grab the sides of the FOUP. The back two retention springs 38' lock into a depression (lip) 38L in the FOUP. This provides a solid grip for the cassette in

FOUP. The

Please replace the paragraph/section beginning on page 4, lines 22-26 to page 5, lines 1-3.

FIG. 3 is a top left view perspective of a semiconductor cassette reducer 20 in accordance with one embodiment of the invention. The cassette reducer 20 fits inside of the FOUP of figure 1. In one embodiment, the FOUP is designed to hold 300mm diameter semiconductor wafers S1 (see Fig. 1) and the cassette reducer 20 holds 200mm diameter semiconductor wafers S2 (see Fig. 3). FIG. 3 shows the semiconductor cassette reducer 20 assembled. The same reference numerals are used for both figures.